

FIG. 1A

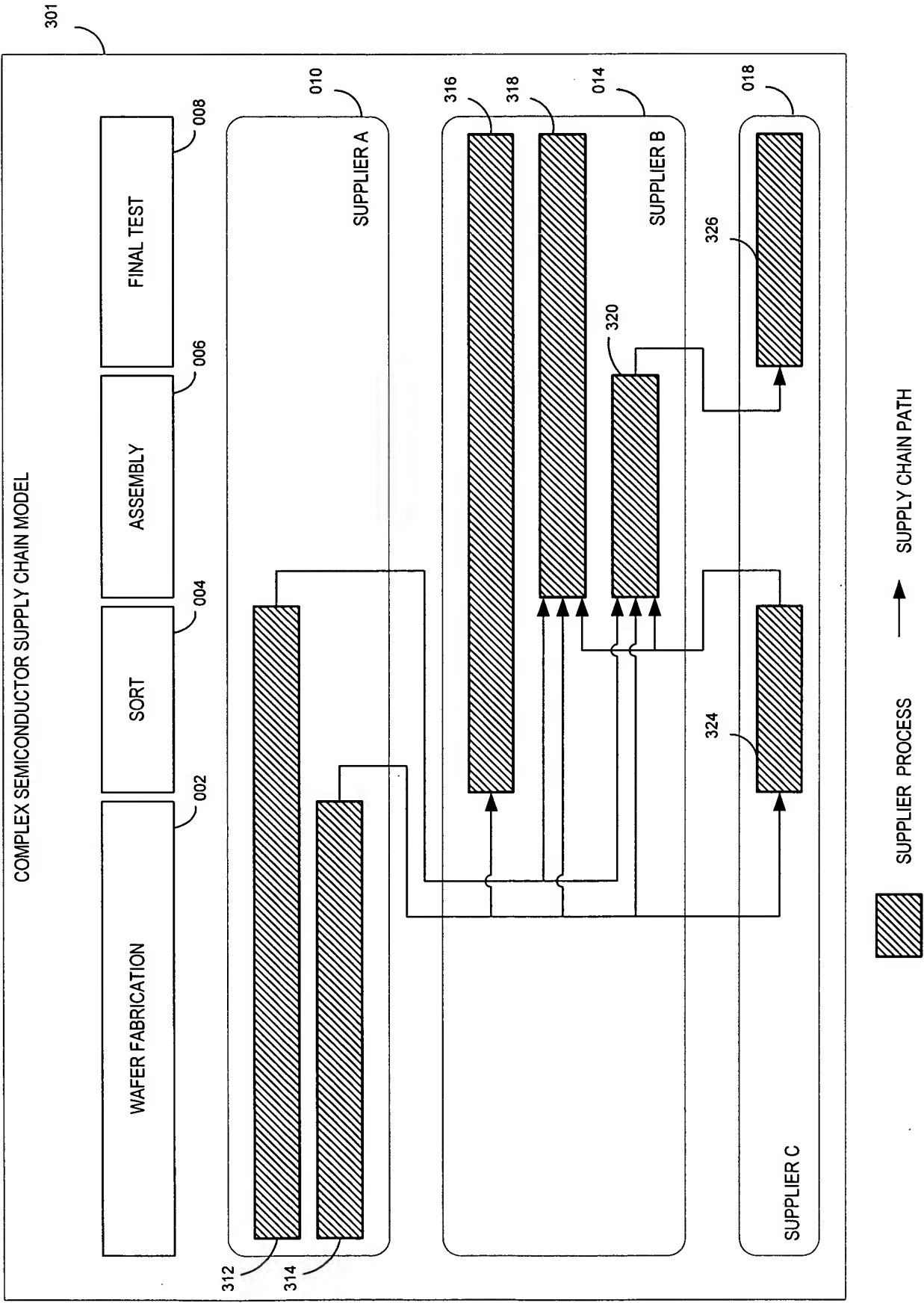


FIG. 1B

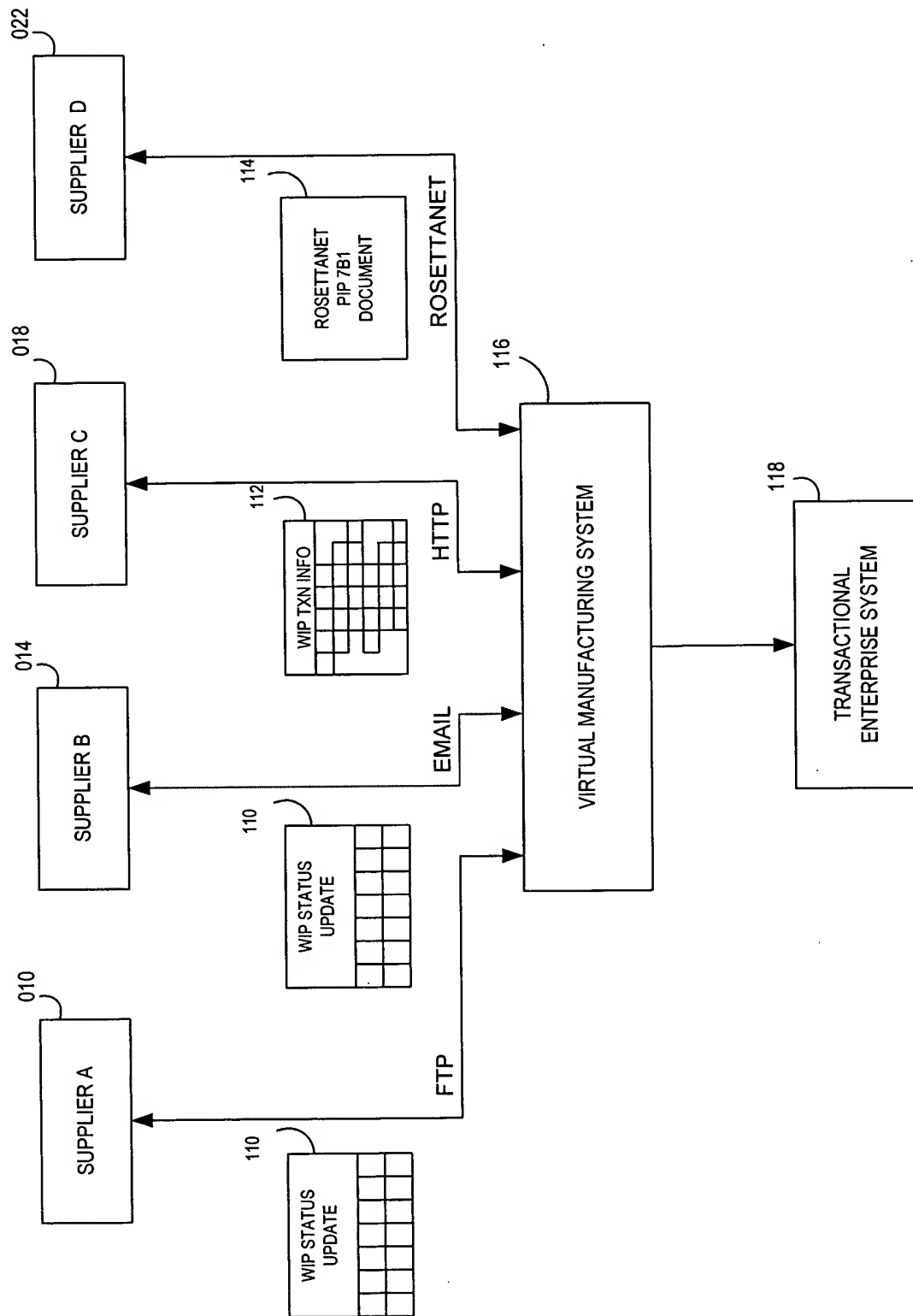


FIG. 2

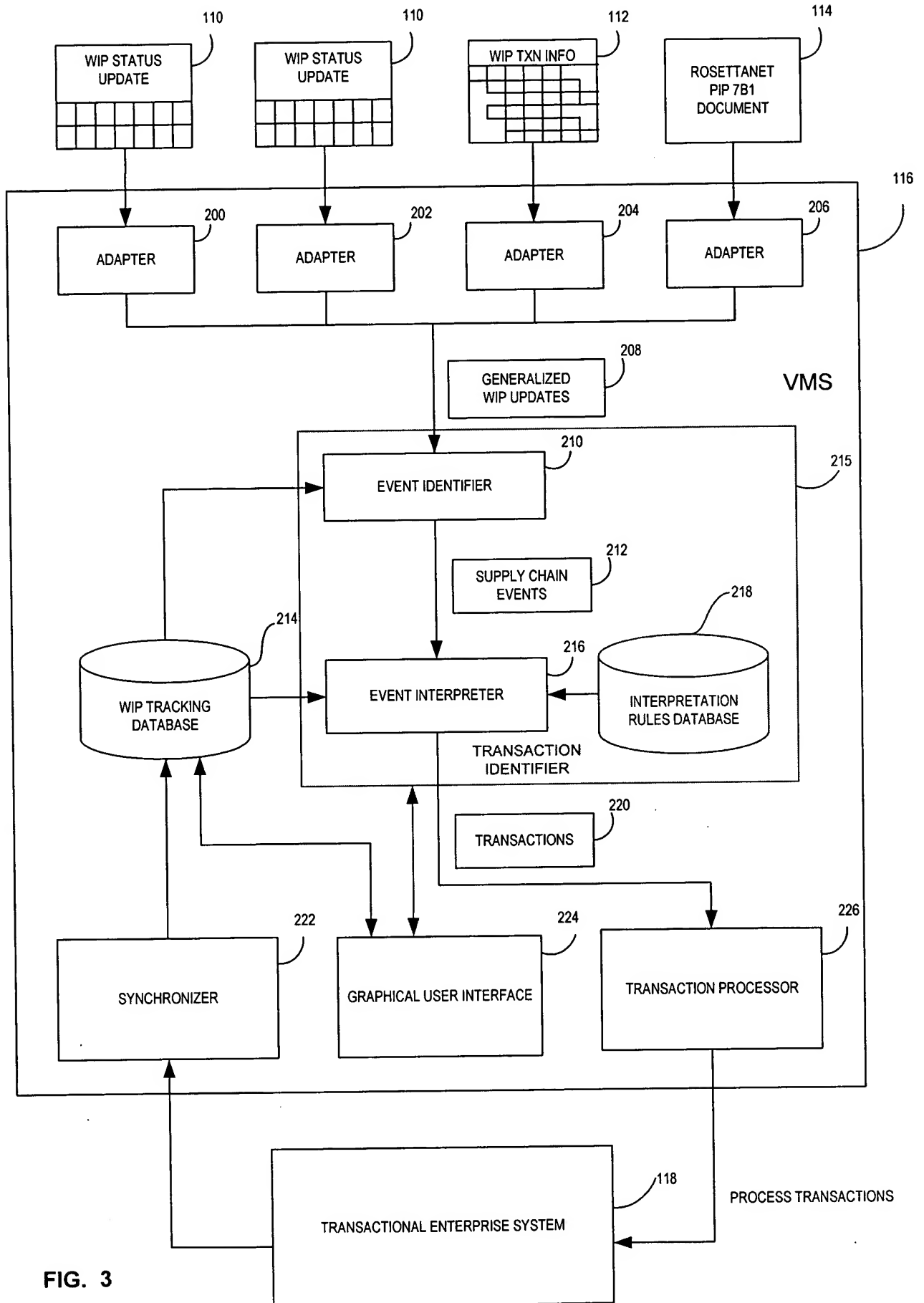


FIG. 3

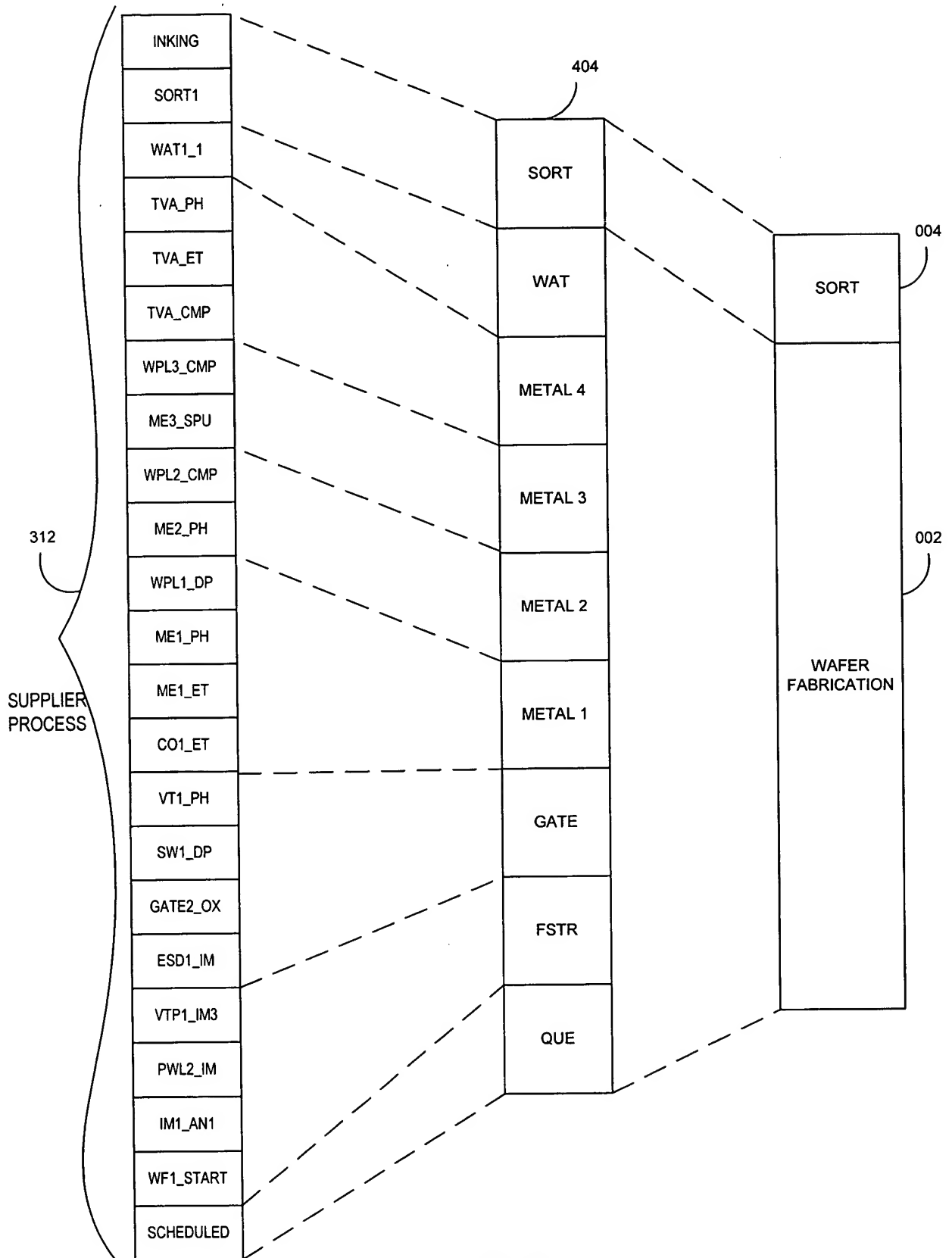


FIG. 4

500

CUSTOMER PRODUCT ID	LOT ID	WAFER QTY	STEP	PROJECTED OUT DATE
EC123456	T041305.1	12	CO1_ET	7/30/2003
EC123456	T041305.3	12	CO1_ET	7/30/2003

FIG. 5A

502

CUSTOMER LOT ID	CUSTOMER PRODUCT ID	LOT ID	WAFER QTY	DIE QTY	STEP	PROJECTED OUT DATE
T041305.1	EC123456	ASD123	6	3000	BANK	8/10/2003
T041305.3	EC123456	ASD124	6	2974	2/O	8/9/2003
T041305.4	EC123456	ASD125	6	2998	D/A	8/9/2003
T041305.5	EC123456	ASD126	6	2980	W/B	8/6/2003

FIG. 5B

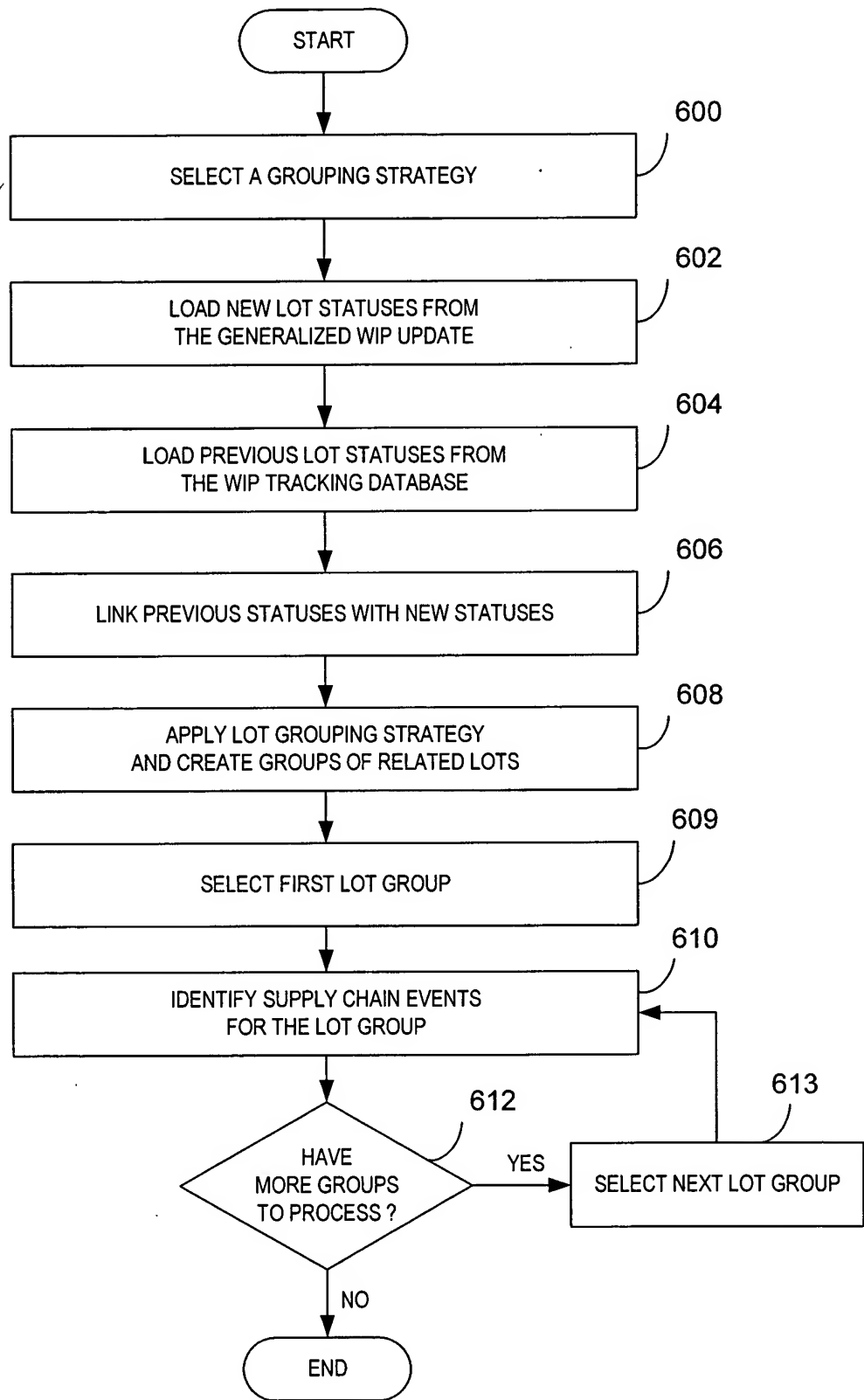


FIG. 6

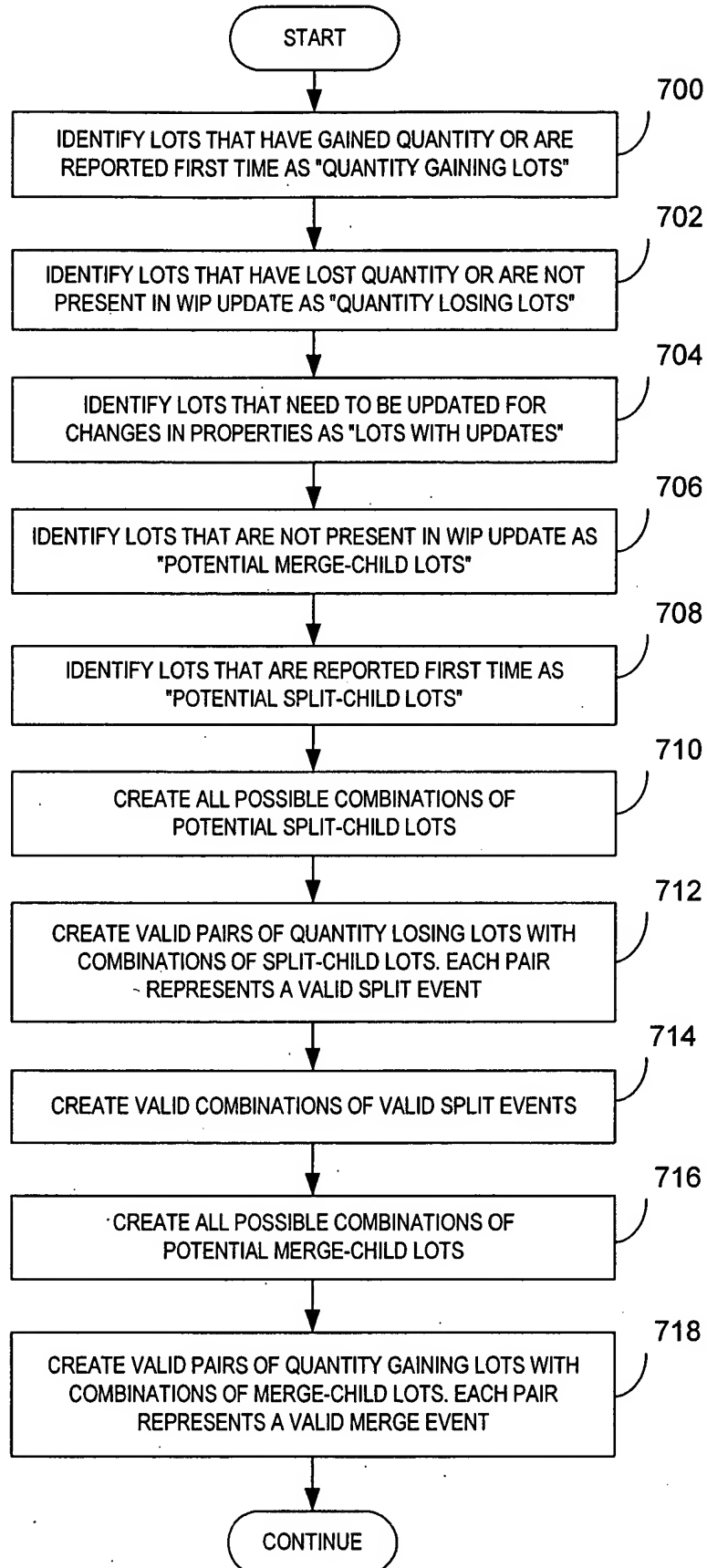


FIG. 7A

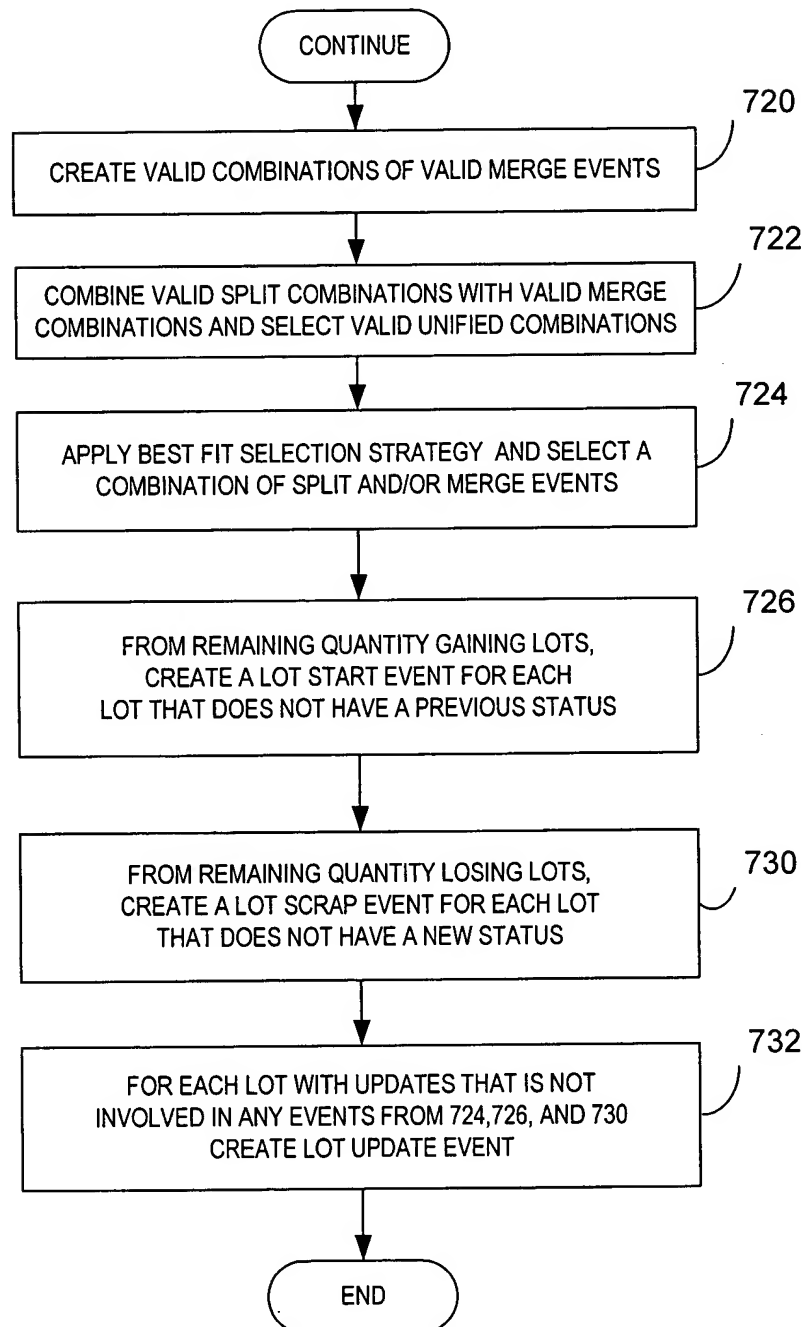


FIG. 7B

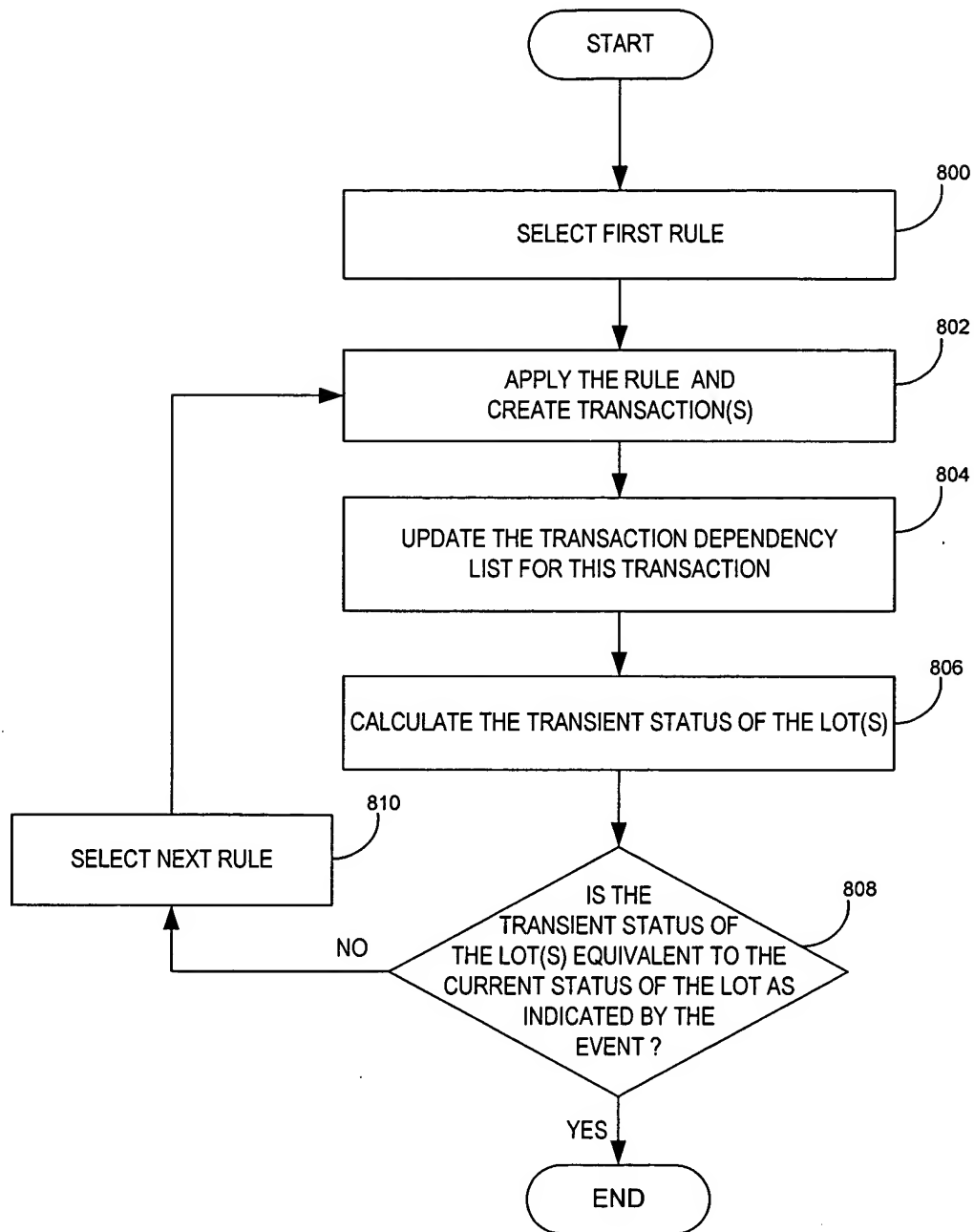


FIG. 8

CUSTOMER PRODUCT ID	LOT ID	WAFER QTY	STEP	PROJECTED OUT DATE
EC123456	T041305.1	25	SCHEDULED	7/30/2003

900

FIG. 9A

CUSTOMER PRODUCT ID	LOT ID	WAFER QTY	STEP	PROJECTED OUT DATE
EC123456	T041305.1	25	WF1_START	7/30/2003

910

FIG. 9B

CUSTOMER PRODUCT ID	LOT ID	WAFER QTY	STEP	PROJECTED OUT DATE
EC123456	T041305.1	12	PWL2_IM	7/30/2003
EC123456	T041305.2	13	PWL2_IM	7/30/2003

920

FIG. 9C

CUSTOMER PRODUCT ID	LOT ID	WAFER QTY	STEP	PROJECTED OUT DATE
EC123456	T041305.1	25	VTP1_IM3	7/30/2003

930

FIG. 9D

CUSTOMER PRODUCT ID	LOT ID	WAFER QTY	STEP	PROJECTED OUT DATE
EC123456	T041305.1	12	CO1_ET	7/30/2003
EC123456	T041305.3	12	CO1_ET	7/30/2003

940

FIG. 9E

CUSTOMER PRODUCT ID	LOT ID	WAFER QTY	STEP	PROJECTED OUT DATE
EC123456	T041305.1	6	ME2_PH	7/30/2003
EC123456	T041305.3	6	WPL2_CMP	7/30/2003
EC123456	T041305.4	6	ME2_PH	7/30/2003
EC123456	T041305.5	6	WPL2_CMP	7/30/2003

950

FIG. 9F

CUSTOMER PRODUCT ID	LOT ID	WAFER QTY	STEP	PROJECTED OUT DATE
EC123456	T041305.1	6	WPL2_CMP	7/30/2003
EC123456	T041305.3	6	WPL2_CMP	7/30/2003
EC123456	T041305.4	6	WPL2_CMP	7/30/2003
EC123456	T041305.5	6	WPL2_CMP	7/30/2003

960

FIG. 9G

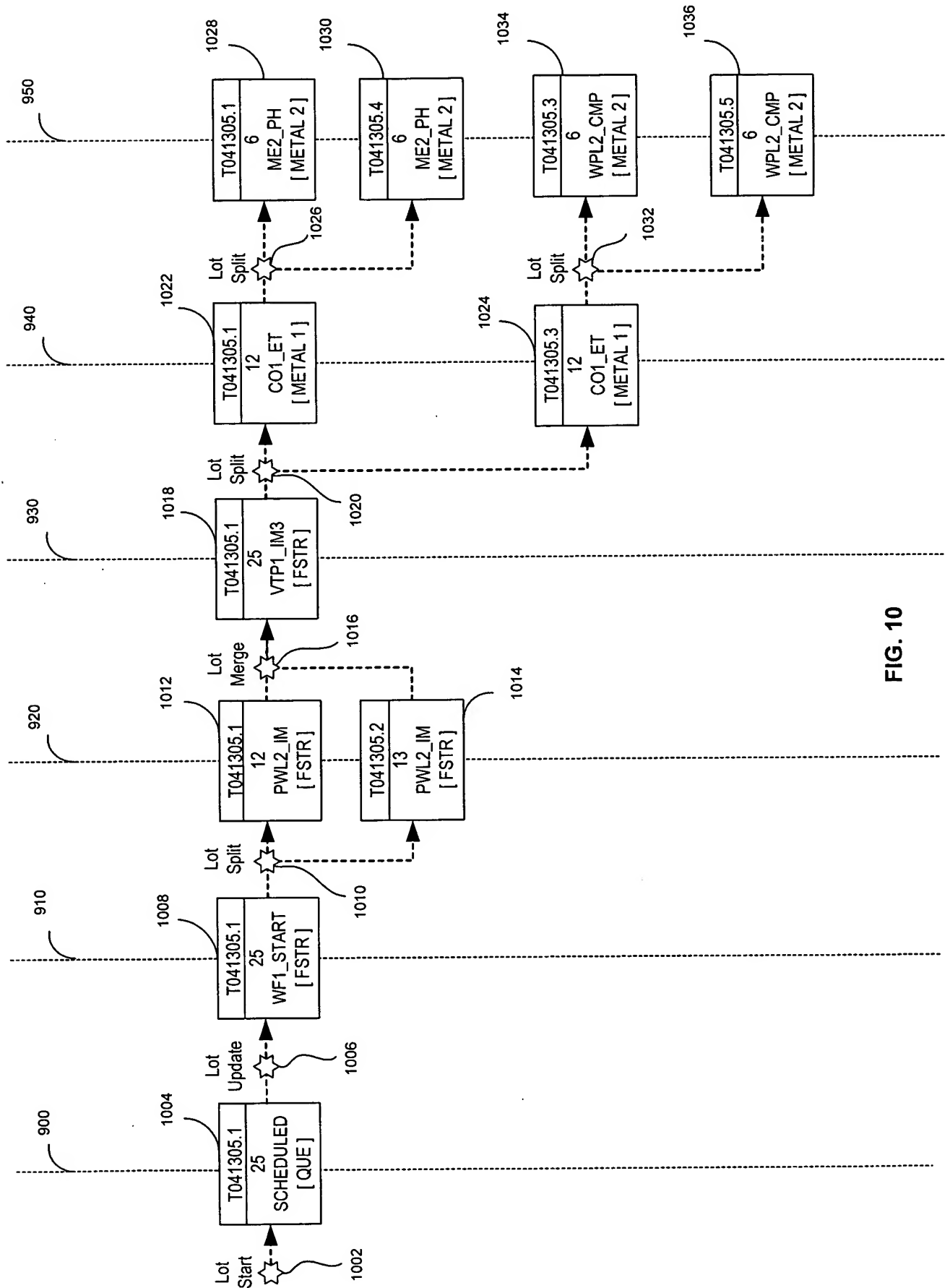


FIG. 10

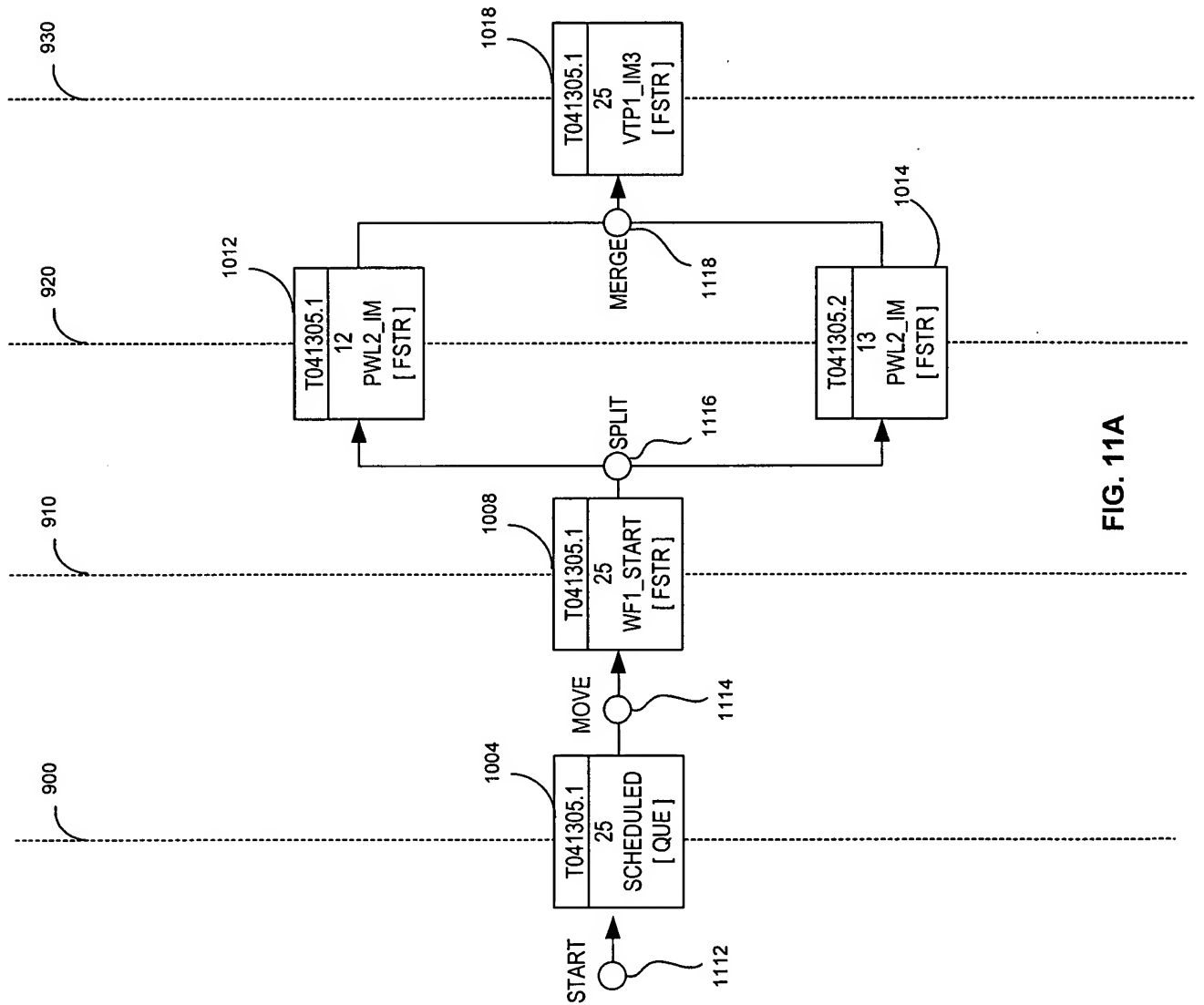


FIG. 11A

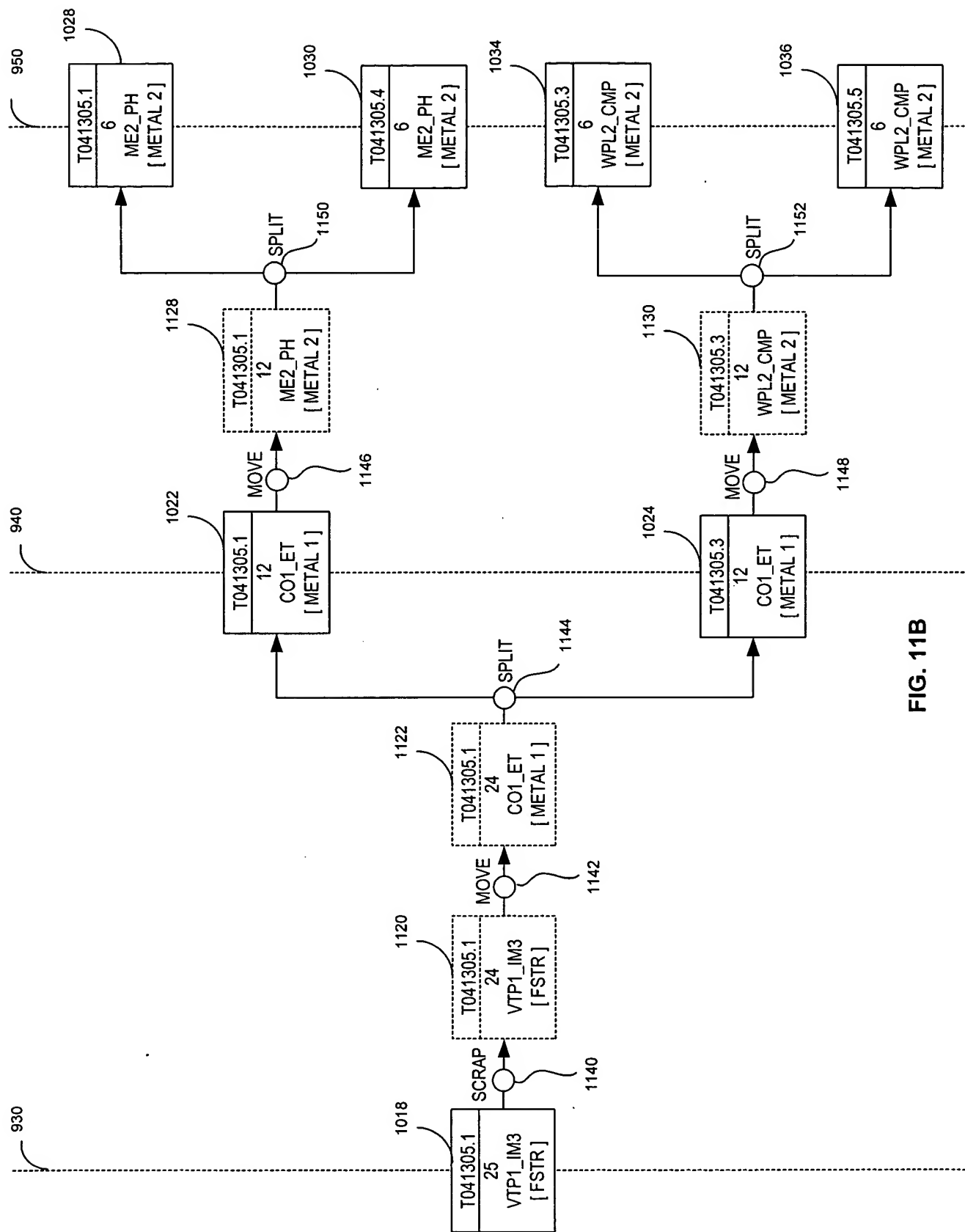


FIG. 11B